

Amendment to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. **(Currently Amended):** A semiconductor device wherein:

a principal surface of a semiconductor base board is ground mirror-finished such that a breakable layer on the principal surface is removed and a crystalline layer which is disposed innermore than the breakable layer is exposed; and

bumps are formed on a predetermined position on ~~other~~ another principal surface of the semiconductor base board.

2. **(Withdrawn):** Method for manufacturing a semiconductor device having the steps for:

grinding a principal surface on a semiconductor base board;

mirror-finishing the principal surface so as to remove a breakable layer on the principal surface and expose a crystalline layer which is disposed innermore than the breakable layer; and

forming bumps on predetermined positions on other principal surface on the semiconductor base board.

3. **(Withdrawn):** Method according to Claim 2 for manufacturing a semiconductor device wherein a principal surface on a semiconductor base board is ground after the other principal surface on the semiconductor base board is coated by a protecting member.